AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-7 (cancelled).

8. (New) A diode, comprising:

a press-fit base including an axially extending mounting region to mount a semiconductor chip;

a head wire provided with a head configured to be affixed to the semiconductor chip; and

a stabilization arrangement which include at least a sleeve and an encapsulating material filling cavities;

wherein the head wire includes a stepped wire connection having a region, which together with the sleeve and the press-fit base forms a housing, the cavities of the housing being filled with encapsulating material.

9. (New) The diode as recited in claim 8, press-fit base, wherein the head wire is made of copper, a surface of the head wire having a nickel or a nickel alloy coating.

10. (New) The diode as recited in claim 9, wherein the coating is made of nickel phosphorus.

11. (New) The diode as recited in claim 8, wherein the encapsulating material is an epoxy.

12. (New)The diode as recited in claim 8, wherein only the head of the head wire, which is inside the housing, is surrounded by the encapsulating material.

13. (New) The diode as recited in claim 8, wherein the head includes at least two regions having different diameters.

14. (New) The diode as recited in claim 8, wherein the head is cone-shaped or bell-shaped.

15. (New) A method for manufacturing a diode, comprising:

providing a press-fit base, the press-fit base including an axially extending mounting region to mount a semiconductor chip;

providing a head wire with a head configured to be affixed to the semiconductor chip, the head wire including a stepped wire connection region;

forming a housing using the stepped wire connection region and a sleeve; and

filling cavities of the housing with an encapsulating material.